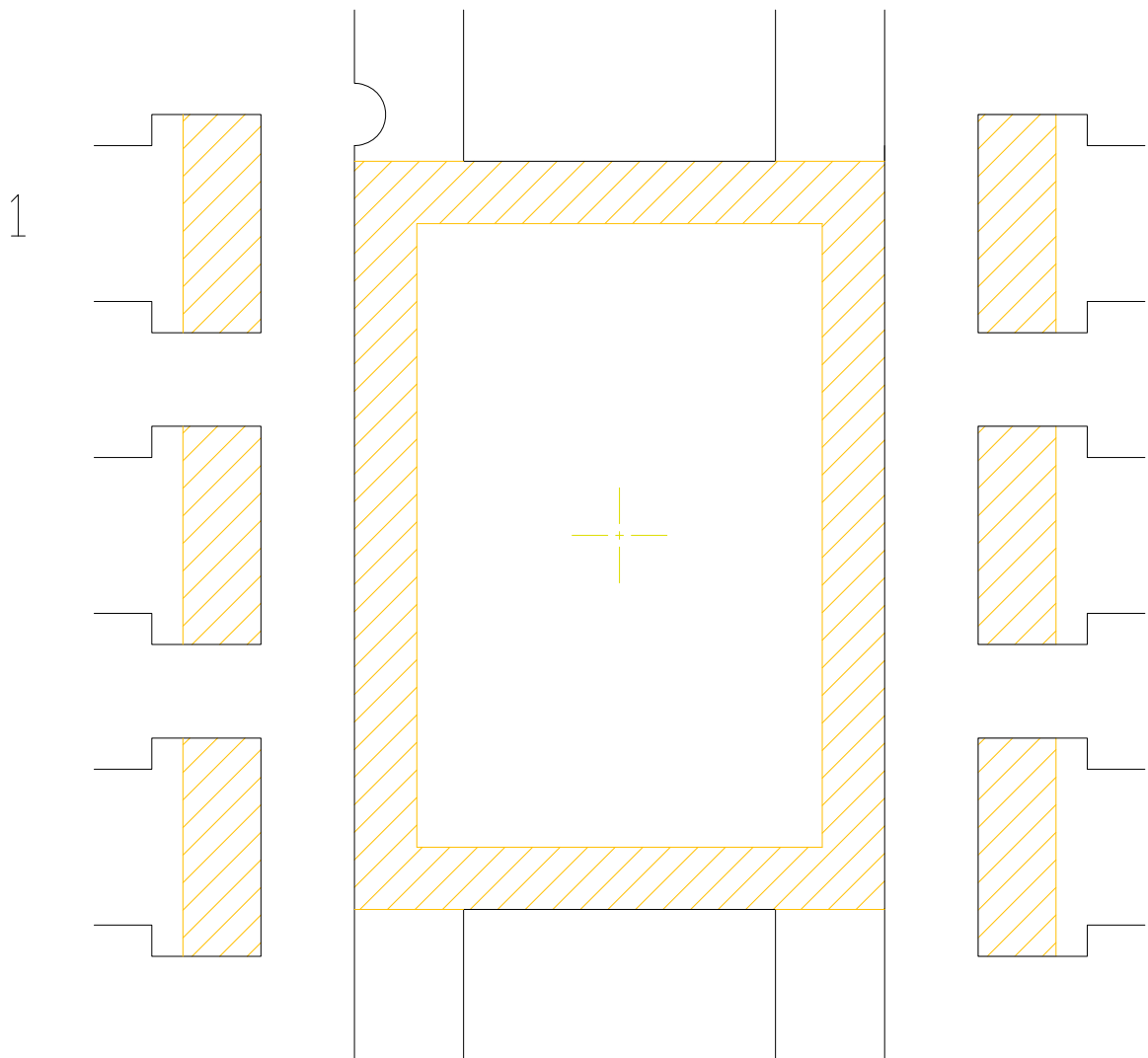


| REVISIONS | | |
|-----------|-----------------|----------|
| REV | DESCRIPTION | DATE |
| B | INITIAL RELEASE | 4-1-2016 |



 NiPdAu PLATING

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| | | |
|-----------------------------|--------------------------------------|-----------------------------------------------------|
| CUSTOMER: xxxxx | DOCUMENT #: | PROMEX INDUSTRIES INC. www.promex-ind.com |
| PROJECT NAME: xxxxx | DIE ATTACH PAD SIZE: 0.85 x 1.20 mm | |
| DIE SIZE, mm: xxxxx | EXPOSED PAD SIZE: 0.70 x 1.20 mm | TITLE DFN 6L 1.5x1.5 mm 0.50 PITCH BOND SHELL |
| DIE THICKNESS, um: xxxxx | DAP PLATING OPTION: GROUND RING | LEADFRAME P/N: 235-00207 |
| BOND PAD PITCH, um: xxxxx | PLATING MATERIAL: NiPdAu | REV A |
| BOND PAD OPENING, um: xxxxx | LEADFRAME MATERIAL: C194 FH | DO NOT SCALE |
| WIRE SIZE, um: xxxxx | LEADFRAME THICKNESS: 0.203±0.0075 mm | FILE NAME 6L-DFN-1.5X1.5-50P-BD.DWG |
| | | SHEET 1 of 1 |